

NTMFS4839NH

Power MOSFET

30 V, 64 A, Single N-Channel, SO-8FL

Features

- Low $R_{DS(ON)}$ to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- Optimized Gate Charge to Minimize Switching Losses
- Low R_G
- These are Pb-Free Devices*

Applications

- Refer to Application Note AND8195/D
- CPU Power Delivery
- DC-DC Converters

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise stated)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DSS}	30	V
Gate-to-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current $R_{\theta JA}$ (Note 1)		$T_A = 25^\circ\text{C}$	15
		$T_A = 85^\circ\text{C}$	11
Power Dissipation $R_{\theta JA}$ (Note 1)		$T_A = 25^\circ\text{C}$	2.17
		$T_A = 85^\circ\text{C}$	1.13
Continuous Drain Current $R_{\theta JA}$ - $t \leq 10$ sec		$T_A = 25^\circ\text{C}$	24
		$T_A = 85^\circ\text{C}$	17
Power Dissipation $R_{\theta JA}$ $t \leq 10$ sec		$T_A = 25^\circ\text{C}$	5.7
		$T_A = 85^\circ\text{C}$	2.9
Continuous Drain Current $R_{\theta JA}$ (Note 2)		$T_A = 25^\circ\text{C}$	9.5
		$T_A = 85^\circ\text{C}$	7.0
Power Dissipation $R_{\theta JA}$ (Note 2)		$T_A = 25^\circ\text{C}$	0.87
		$T_A = 85^\circ\text{C}$	0.45
Continuous Drain Current $R_{\theta JC}$ (Note 1)		$T_C = 25^\circ\text{C}$	64
		$T_C = 85^\circ\text{C}$	46
Power Dissipation $R_{\theta JC}$ (Note 1)		$T_C = 25^\circ\text{C}$	42.4
		$T_C = 25^\circ\text{C}$	22
Pulsed Drain Current	$T_A = 25^\circ\text{C}$, $t_p = 10 \mu\text{s}$	I_{DM}	192
Operating Junction and Storage Temperature		T_J	-55 to
		T_{STG}	+150
Source Current (Body Diode)	I_S	35	A
Drain to Source dV/dt	dV/dt	6	V/ns
Single Pulse Drain-to-Source Avalanche Energy ($T_J = 25^\circ\text{C}$, $V_{DD} = 24$ V, $V_{GS} = 10$ V, $I_L = 27$ A, $L = 0.3$ mH, $R_G = 25 \Omega$)	EAS	109	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)	T_L	260	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

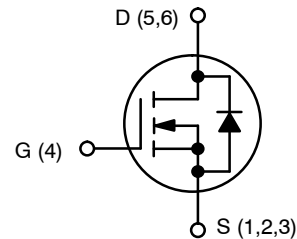
1. Surface-mounted on FR4 board using 1 sq-in pad, 1 oz Cu.
 2. Surface-mounted on FR4 board using the minimum recommended pad size.
- *For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



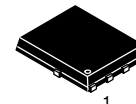
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$V_{(BR)DSS}$	$R_{DS(ON)}$ MAX	I_D MAX
30 V	5.5 m Ω @ 10 V	64 A
	10.3 m Ω @ 4.5 V	

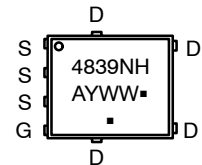


N-CHANNEL MOSFET



SO-8 FLAT LEAD
CASE 488AA
STYLE 1

MARKING DIAGRAM



- A = Assembly Location
 - Y = Year
 - WW = Work Week
 - = Pb-Free Package
- (Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
NTMFS4839NHT1G	SO-8FL (Pb-Free)	1500 / Tape & Reel
NTMFS4839NHT3G	SO-8FL (Pb-Free)	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case (Drain)	$R_{\theta JC}$	2.95	°C/W
Junction-to-Ambient – Steady State (Note 3)	$R_{\theta JA}$	57.6	
Junction-to-Ambient – Steady State (Note 4)	$R_{\theta JA}$	143.3	
Junction-to-Ambient ($t \leq 10$ sec)	$R_{\theta JA}$	22	

3. Surface-mounted on FR4 board using 1 sq-in pad, 1 oz Cu.
4. Surface-mounted on FR4 board using the minimum recommended pad size.

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	30			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$			27.5		mV/°C
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS} = 0\text{ V}, V_{DS} = 24\text{ V}$	$T_J = 25^\circ\text{C}$		1	μA
			$T_J = 125^\circ\text{C}$		10	
Gate-to-Source Leakage Current	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			± 100	nA

ON CHARACTERISTICS (Note 5)

Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\ \mu\text{A}$	1.5	2.1	2.5	V	
Negative Threshold Temperature Coefficient	$V_{GS(TH)}/T_J$			5.5		mV/°C	
Drain-to-Source On Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V to } 11.5\text{ V}$	$I_D = 30\text{ A}$		4.3	5.5	mΩ
			$I_D = 15\text{ A}$		4.3		
		$V_{GS} = 4.5\text{ V}$	$I_D = 30\text{ A}$		8.2	10.3	
			$I_D = 15\text{ A}$		7.8		
Forward Transconductance	g_{FS}	$V_{DS} = 1.5\text{ V}, I_D = 50\text{ A}$		60		S	

CHARGES, CAPACITANCES & GATE RESISTANCE

Input Capacitance	C_{ISS}	$V_{GS} = 0\text{ V}, f = 1\text{ MHz}, V_{DS} = 12\text{ V}$		1744	2354	pF
Output Capacitance	C_{OSS}			355	479	
Reverse Transfer Capacitance	C_{RSS}			191	296	
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 4.5\text{ V}, V_{DS} = 15\text{ V}; I_D = 30\text{ A}$		12.9	19.5	nC
Threshold Gate Charge	$Q_{G(TH)}$			2.2	3.3	
Gate-to-Source Charge	Q_{GS}			5.2	7.8	
Gate-to-Drain Charge	Q_{GD}			5.4	8.0	
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 11.5\text{ V}, V_{DS} = 15\text{ V}; I_D = 30\text{ A}$		31	43.5	nC

SWITCHING CHARACTERISTICS (Note 6)

Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = 4.5\text{ V}, V_{DS} = 15\text{ V}, I_D = 15\text{ A}, R_G = 3.0\ \Omega$		13.4	20	ns
Rise Time	t_r			22.5	33.7	
Turn-Off Delay Time	$t_{d(OFF)}$			16	24	
Fall Time	t_f			5.3	7.9	

5. Pulse Test: pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$.
6. Switching characteristics are independent of operating junction temperatures.

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ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
SWITCHING CHARACTERISTICS (Note 6)						
Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = 11.5\text{ V}, V_{DS} = 15\text{ V},$ $I_D = 15\text{ A}, R_G = 3.0\ \Omega$		8.1	12.2	ns
Rise Time	t_r			19.6	29.4	
Turn-Off Delay Time	$t_{d(OFF)}$			23.2	34.9	
Fall Time	t_f			3.4	5.1	

DRAIN-SOURCE DIODE CHARACTERISTICS

Forward Diode Voltage	V_{SD}	$V_{GS} = 0\text{ V},$ $I_S = 30\text{ A}$	$T_J = 25^\circ\text{C}$		0.83	1.2	V
			$T_J = 125^\circ\text{C}$		0.73		
Reverse Recovery Time	t_{RR}	$V_{GS} = 0\text{ V}, dI_S/dt = 100\text{ A}/\mu\text{s},$ $I_S = 30\text{ A}$			19.3		ns
Charge Time	t_a				10.1		
Discharge Time	t_b				9.2		
Reverse Recovery Charge	Q_{RR}				6.3		

PACKAGE PARASITIC VALUES

Source Inductance	L_S	$T_A = 25^\circ\text{C}$		0.93		nH
Drain Inductance	L_D			0.005		nH
Gate Inductance	L_G			1.84		nH
Gate Resistance	R_G			0.9		Ω

5. Pulse Test: pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$.

6. Switching characteristics are independent of operating junction temperatures.

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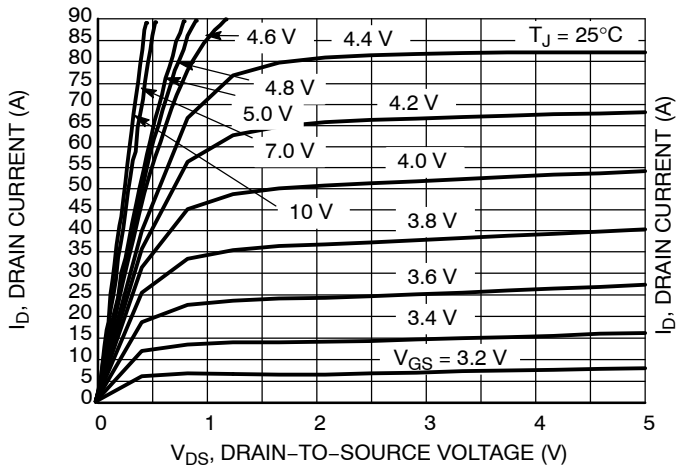


Figure 1. On-Region Characteristics

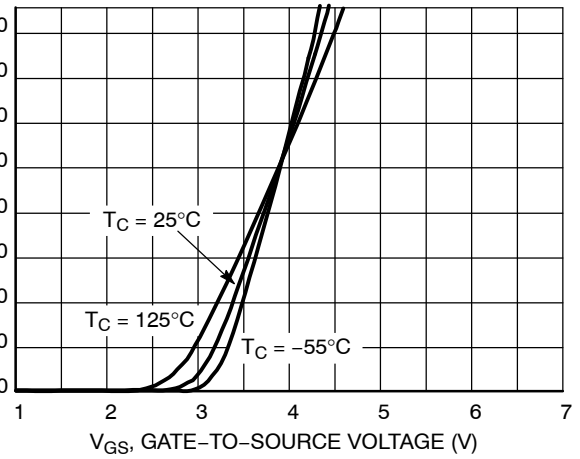


Figure 2. Transfer Characteristics

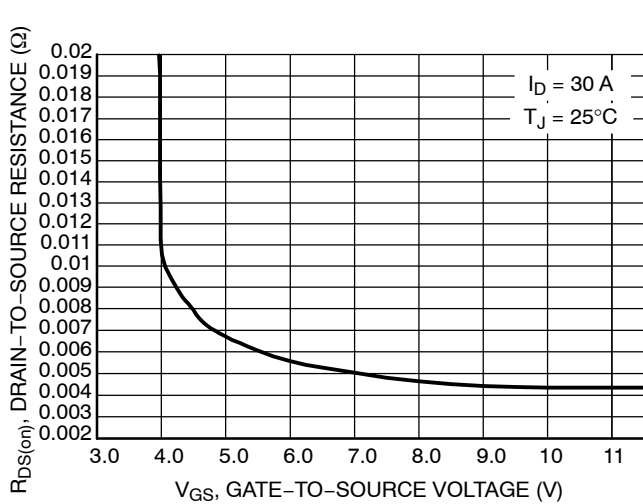


Figure 3. On-Resistance versus Gate-to-Source Voltage

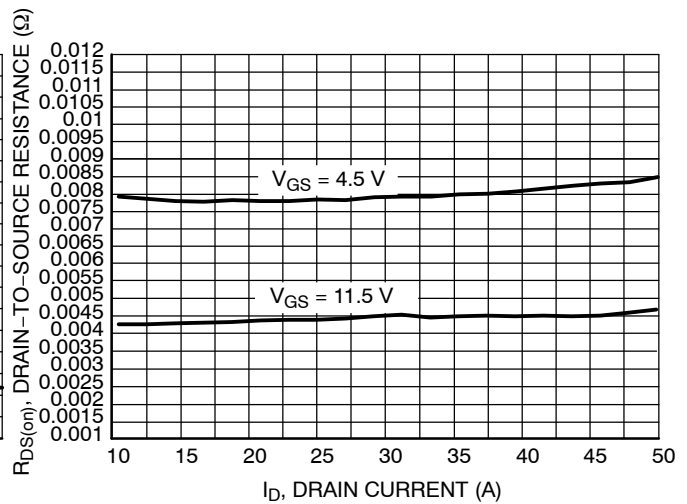


Figure 4. On-Resistance versus Drain Current and Gate Voltage

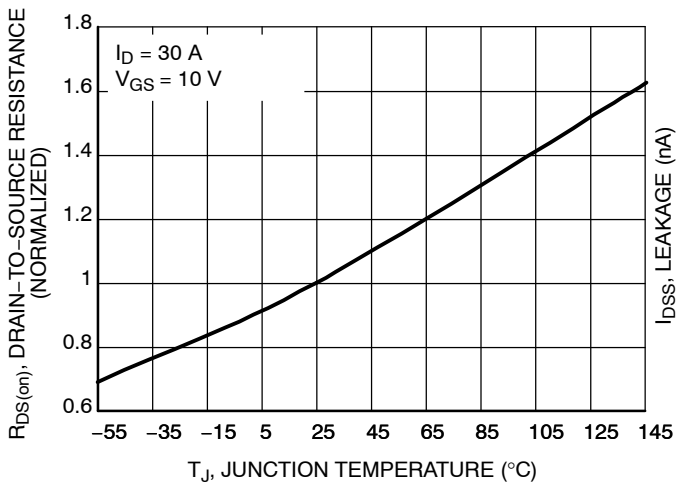


Figure 5. On-Resistance Variation with Temperature

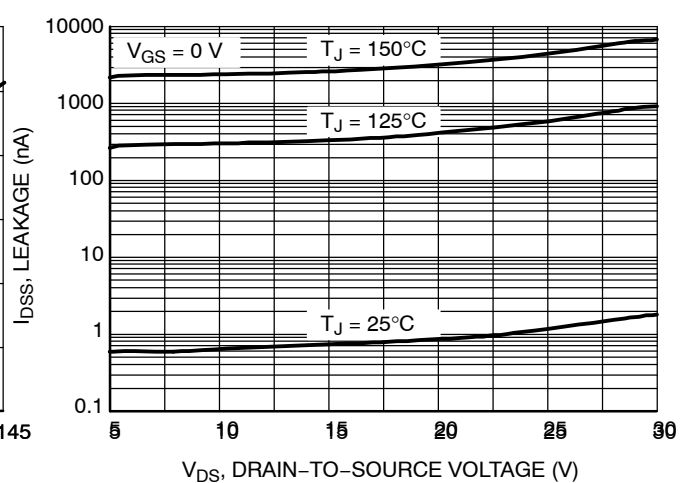
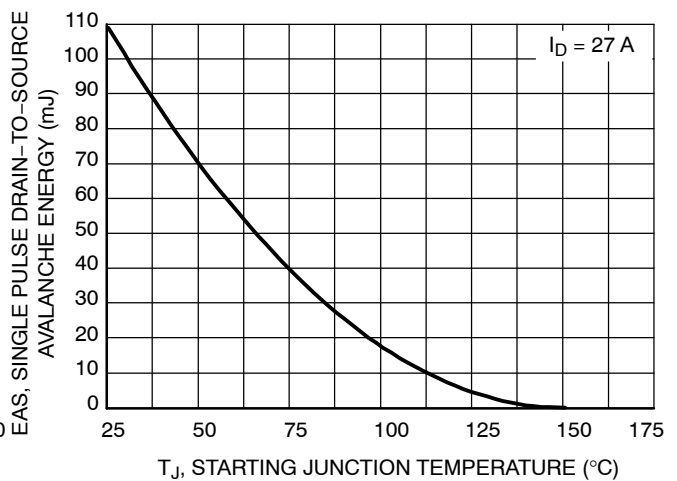
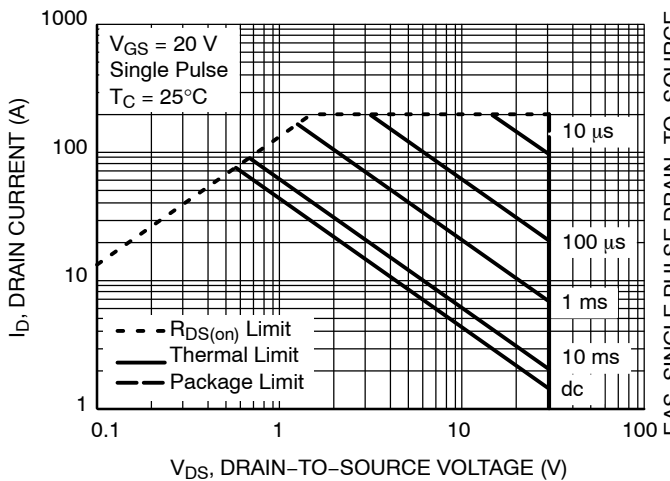
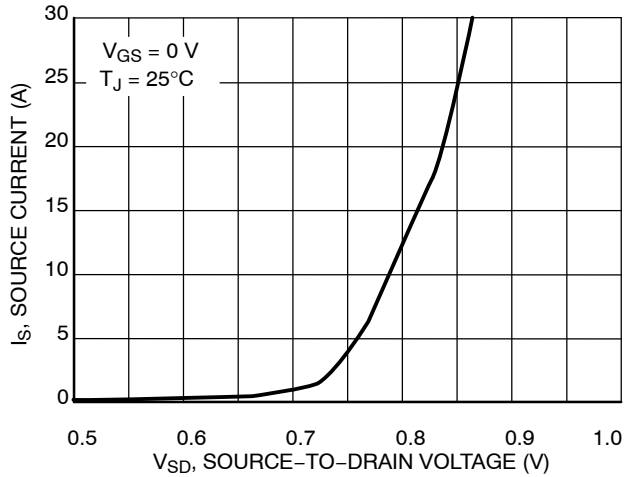
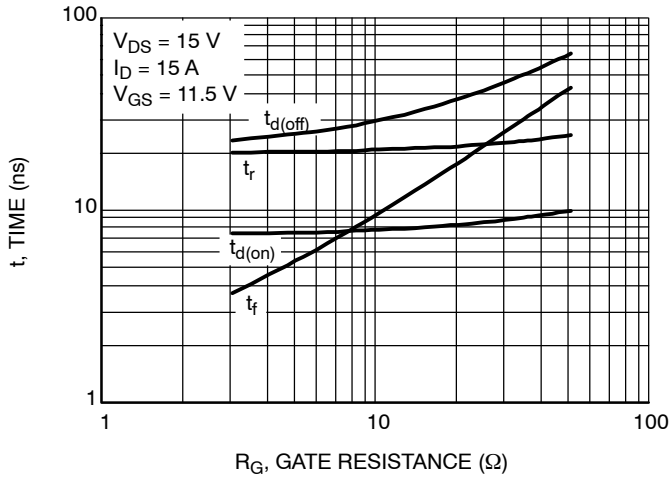
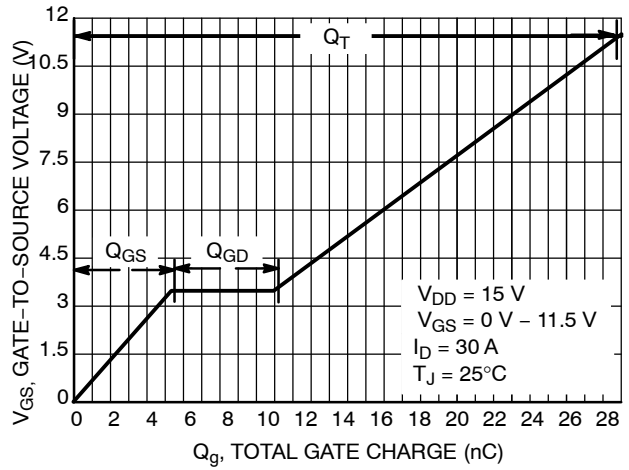
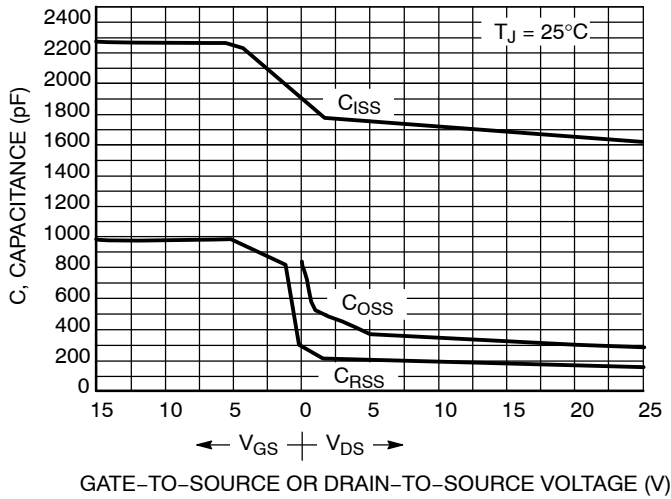


Figure 6. Drain-to-Source Leakage Current versus Voltage

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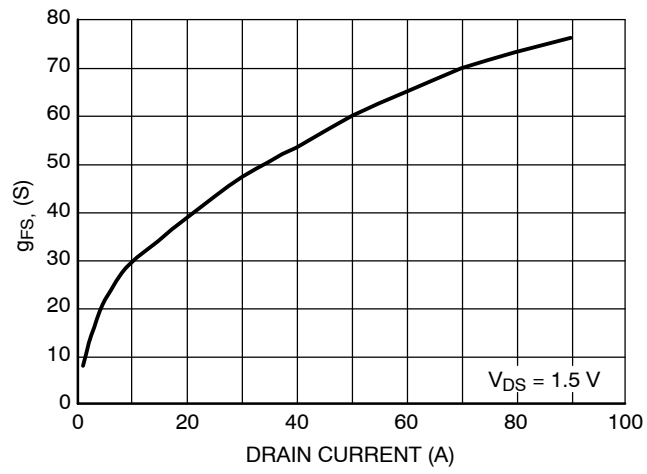


Figure 13. g_{FS} versus Drain Current

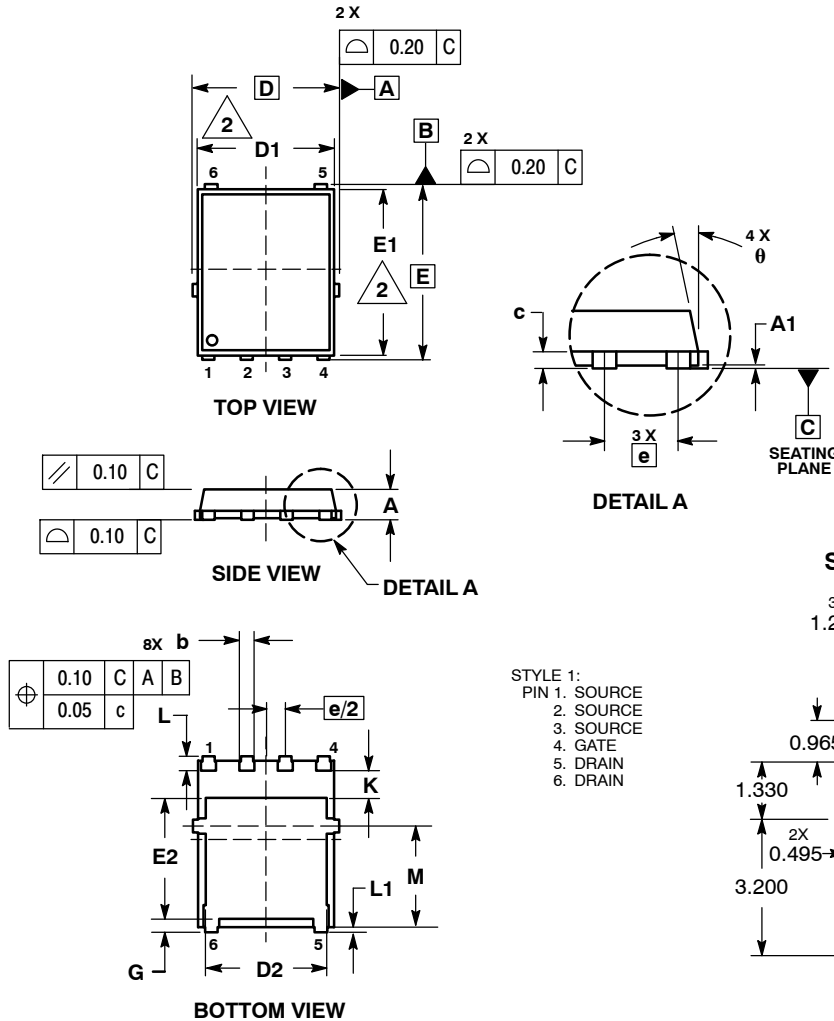
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PACKAGE DIMENSIONS

DFN5 5x6, 1.27P
(SO-8FL)
CASE 488AA-01
ISSUE D

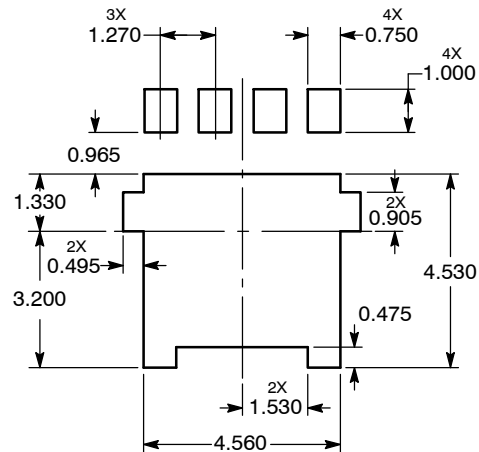
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.



DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.00	---	0.05
b	0.33	0.41	0.51
c	0.23	0.28	0.33
D	5.15 BSC		
D1	4.50	4.90	5.10
D2	3.50	---	4.22
E	6.15 BSC		
E1	5.50	5.80	6.10
E2	3.45	---	4.30
e	1.27 BSC		
G	0.51	0.61	0.71
K	0.51	---	---
L	0.51	0.61	0.71
L1	0.05	0.17	0.20
M	3.00	3.40	3.80
θ	0°	---	12°

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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